

**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

1. (Currently Amended) A method for manufacturing a USB electronic key, whereby a microcircuit is cut out from a tape having a plurality of microcircuits, each microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads; said method ~~being characterized in that it further comprises~~ comprising the following step whereby, in a single operation, the thickness of the microcircuit is adjusted at least in the area of the contact pads, so as to have a thickness that conforms to the USB Standard.

2. (Currently Amended) A manufacturing method according to claim 1, ~~characterized in that wherein~~ the adjustment is achieved by a casing (~~64, 66, 67, 68~~) comprising at least one bottom half-shell (~~66~~) disposed at least under the contact pads (~~57~~).

3. (Currently Amended) A manufacturing method according to claim 2, ~~characterized in that wherein~~ the bottom half-shell is interfitted with a top half-shell (~~67~~) covering a zone of the microcircuit (~~62~~) that lies outside the contact pads.

4. (Currently Amended) A manufacturing method according to claim 1, ~~characterized in that wherein~~ the adjustment is achieved by inserting the microcircuit into a shell (~~68~~) having an access (~~69~~) on a rear edge.

5. (Currently Amended) A manufacturing method according to claim 1, ~~characterized in that wherein~~ the adjustment is achieved by forming an overmolded portion (~~64~~) over the microcircuit (~~100~~).

6. (Currently Amended) A manufacturing method according to claim 1, ~~characterized in that wherein~~ the microcircuit is fastened to the bottom shell (~~66~~).

7. (Currently Amended) A manufacturing method according to claim 6, ~~characterized in that wherein~~ the microcircuit is fastened by adhesive bonding or by tight-fitting cross-wise at least.

8. (Currently Amended) A manufacturing method according to ~~any preceding claim, characterized in that~~ claim 1, wherein the electronic component is disposed at a location offset from a location (63) of the contact pads.

9. (Currently Amended) A manufacturing method according to ~~any preceding claim, characterized in that~~ claim 1, wherein the electronic component is disposed on the same top face of the microcircuit as the contact pads.

10. (Currently Amended) An electronic key including a microcircuit defining USB-format contact pads and carrying at least one electronic component (60, 64) connected to the pads, ~~said electronic key being characterized in that~~ wherein the contact pads (57) are disposed on a dielectric having a thickness of less than 200  $\mu\text{m}$ ; and ~~in that it has its~~ thickness is adjusted by portion (66) of material overmolded over the microcircuit, at least in the area of and below a location of the contact pads, so that its microcircuit thickness conforms to the USB Standard.

11. (Currently Amended) An electronic key according to claim 10, ~~characterized in that~~ wherein the overmolded portion is suitable for subsequently receiving a covering.

12. (Currently Amended) An electronic key comprising a microcircuit defining USB-format contact pads and carrying an electronic component connected to the pads, ~~said electronic key being characterized in that~~ wherein the contact pads (57) are disposed on a dielectric having a thickness of less than 200  $\mu\text{m}$ ; and ~~in that it has its~~ microcircuit thickness is adjusted by a bottom shell (66), at least in the area of a location (63) of the contact pads, so that its microcircuit thickness conforms to the USB Standard.

13. (Currently Amended) An electronic key according to claim 11, ~~characterized in that~~ wherein the bottom half-shell is interfitted with a top half-shell (67) which covers a zone (62) of the microcircuit that lies outside the location (63) of the contact pads.

14. (Currently Amended) An electronic key according to claim 12 ~~or claim 13, characterized in that~~ , wherein it has an access (69) for inserting the microcircuit on a rear edge of its shell.